



SSC8L3410GN4

Dual N-Channel Enhancement MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	I _D
40V	±20V	8.5mΩ@10V	32A
		11.3mΩ@4.5V	

Description

The device is N-Channel enhancement mode MOSFET. Uses SGT Technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC - DC conversion, power switch and charging circuit.

100% UIS + ΔVDS + Rg Tested!

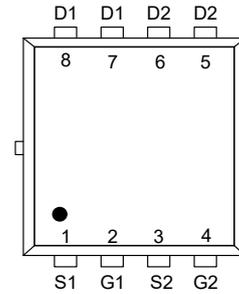
Applications

- Inverter
- DC-DC Converter
- Half and Full Bridge Topology
- Motor Drive Control

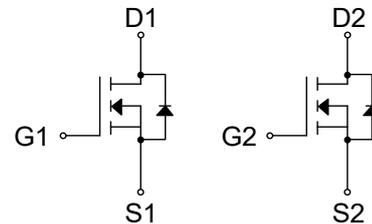
Ordering Information

Device	Package	Shipping
SSC8L3410GN4	PDFN3.3X3.3-8L	5000/Reel

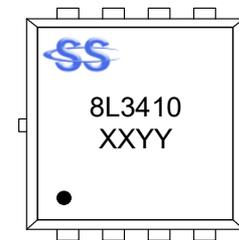
Pin configuration



PDFN3.3x3.3-8L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ **Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit	
V_{DSS}	Drain-to-Source Voltage	40	V	
V_{GSS}	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current ^b	$T_C = 25^\circ\text{C}$	32	A
		$T_C = 100^\circ\text{C}$	20	A
I_{DSM}	Continuous Drain Current ^a	$T_A = 25^\circ\text{C}$	11	A
		$T_A = 70^\circ\text{C}$	8	A
I_{DM}	Pulsed Drain Current ^b	140	A	
P_D	Power Dissipation ^c	$T_C = 25^\circ\text{C}$	21	W
		$T_C = 100^\circ\text{C}$	8.6	W
P_{DSM}	Power Dissipation ^a	$T_A = 25^\circ\text{C}$	2.3	W
		$T_A = 70^\circ\text{C}$	1.45	W
I_{AS}	Avalanche Current ^b $L = 0.5\text{mH}$	12	A	
E_{AS}	Avalanche Energy ^b $L = 0.5\text{mH}$	36	mJ	
T_J	Operation junction temperature	-55 to 150	$^\circ\text{C}$	
T_{STG}	Storage temperature range	-55 to 150	$^\circ\text{C}$	

➤ **Thermal Resistance Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	55	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	5.8	

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

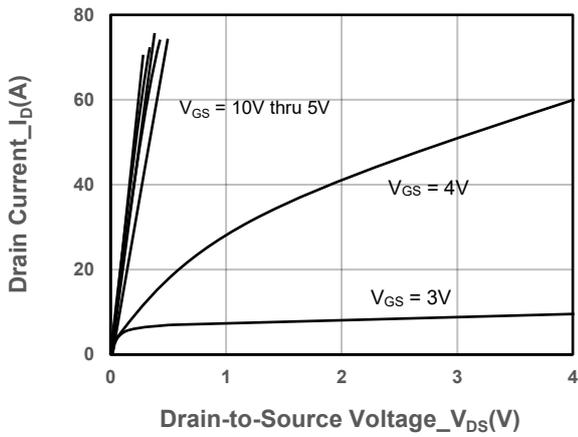


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

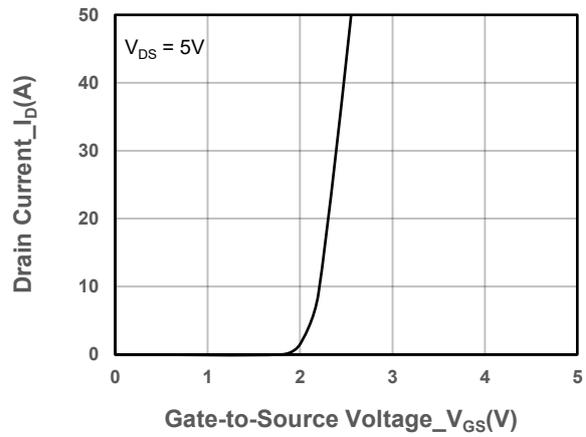
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1	1.7	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 12A		8.5	13	mΩ
		V _{GS} = 4.5V, I _D = 10A		11.3	17	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 1A			1.2	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.3		Ω
Input Capacitance	C _{ISS}	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz		648		pF
Output Capacitance	C _{OSS}			360		
Reverse Transfer Capacitance	C _{RSS}			4		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 20V, I _D = 12A		11.5		nC
Gate to Source Charge	Q _{GS}			2.1		
Gate to Drain Charge	Q _{GD}			2.2		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 15V, I _D = 1A, R _G = 3.3Ω		8		ns
Rise Time	T _r			6		
Turn-off Delay Time	T _{D(OFF)}			34		
Fall Time	T _f			10		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=500A/us		25		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=500A/us		60		nC



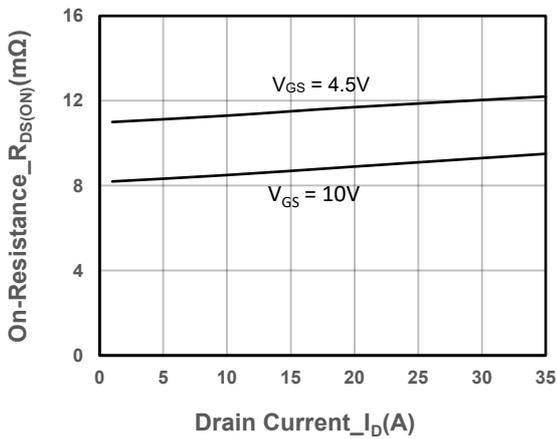
➤ **Typical Performance Characteristics (T_A=25°C unless otherwise noted)**



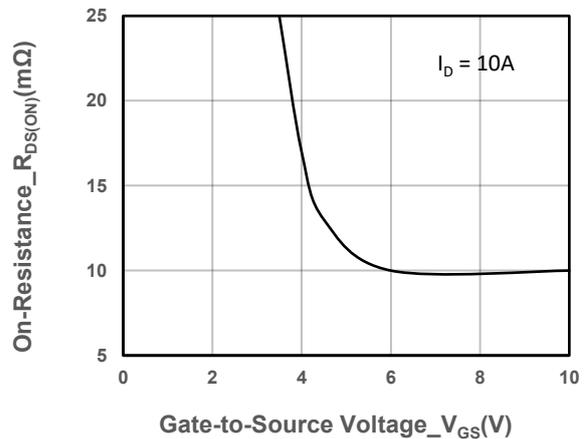
Output Characteristics



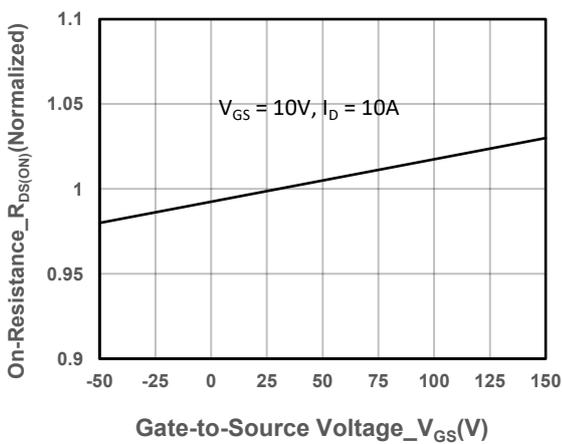
Transfer Characteristics



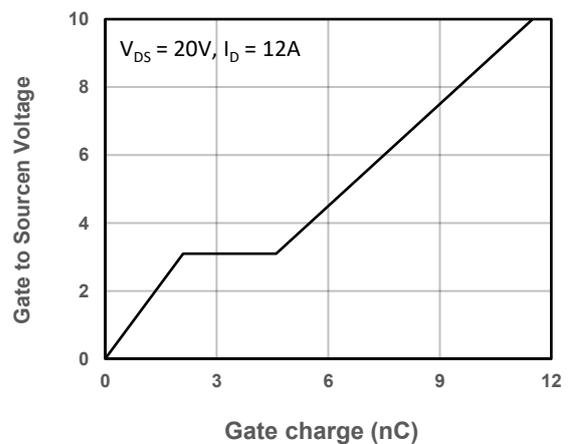
On-Resistance vs. Drain Current and Gate Voltage



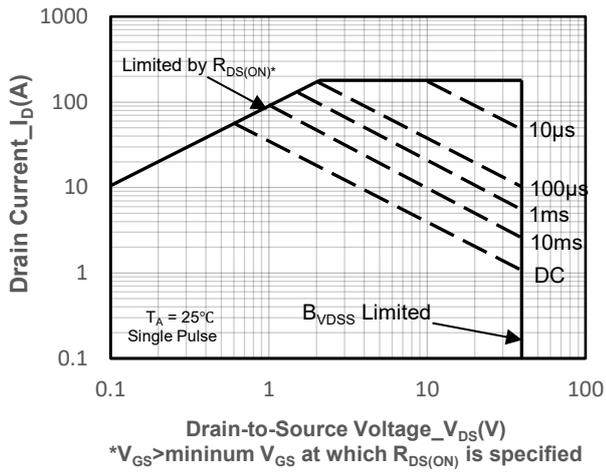
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



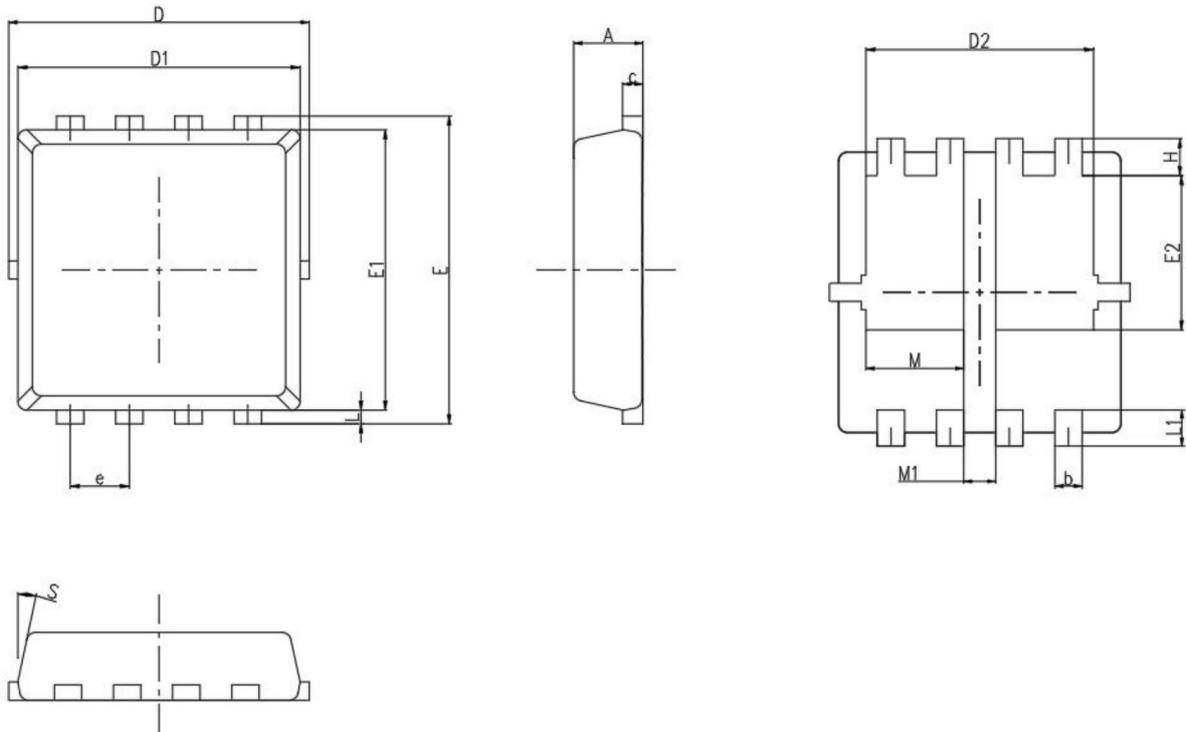
Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient



➤ Package Information



Symbol	MILL IMETER		
	Min	Nom	Max
A	0.60	0.75	0.90
b	0.25	0.30	0.35
c	0.10	0.20	0.30
D	3.00	3.20	3.45
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.10	3.30	3.50
E1	2.90	3.05	3.20
E2	1.55	1.75	1.95
e	0.65BSC		
H	0.20	0.40	0.57
L	0.06	0.10	0.20
L1	0.30	0.40	0.55
S	10°	12°	14°
M	0.95	1.05	1.15
M1	0.4BSC		



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